

General Description

The Sanrise SRT04N037L is a low voltage power MOSFET, fabricated using advanced split gate trench technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density.

The SRT04N037L break down voltage is 40V and it has a high rugged avalanche characteristics. The SRT04N037L is available in PDFN5*6 and PDFN3.3*3.3 packages.

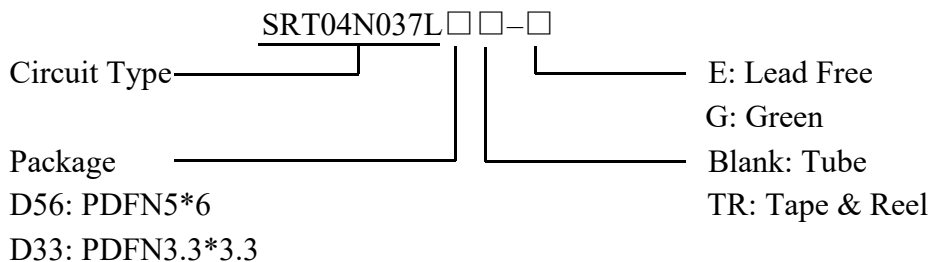
Features

- Ultra Low
 $R_{DS(ON_TYP)} = 3.25m\Omega, PDFN5*6 @ V_{GS} = 10V.$
 $R_{DS(ON_TYP)} = 3.55m\Omega, PDFN3.3*3.3 @ V_{GS} = 10V.$
- Ultra Low Gate Charge, $Q_g = 26nC$ typ.
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- Motor Driver
- E-Tools
- BMS
- Synchronous Rectifier

Ordering Information



Package	Part Number	Marking ID	Packing Type
PDFN5*6	SRT04N037LD56TR-G	SRT04N037LD56G	Tape & Reel
PDFN3.3*3.3	SRT04N037LD33TR-G	04N037LD33G	Tape & Reel

Symbol

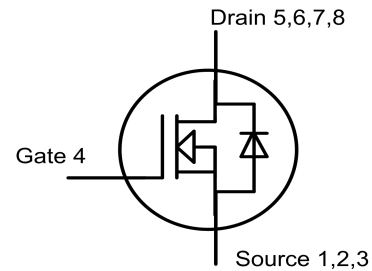


Figure 1 Symbol of SRT04N037L

Package Type

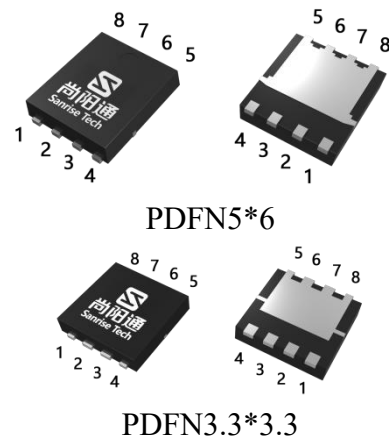


Figure 2 Package Type of SRT04N037L

Absolute Maximum Ratings

Parameter		Symbol	Rating		Unit
Drain-Source Voltage		V_{DSS}	40		V
Gate-Source Voltage		V_{GSS}	±20		V
Continuous Drain Current, Package Limited	$T_C=25^{\circ}C$	I_D	PDFN5*6	80	A
			PDFN3.3*3.3	60	
	$T_C=125^{\circ}C$		PDFN5*6	40	
			PDFN3.3*3.3	38	
Continuous Drain Current, Silicon	$T_C=25^{\circ}C$		PDFN5*6	90	
			PDFN3.3*3.3	86	
Pulsed Drain Current (Note 2)		I_{DM}	PDFN5*6	240	A
			PDFN3.3*3.3	180	
Power Dissipation ($T_C = 25^{\circ}C$)		P_D	54		W
Avalanche Destructive Energy, Single Pulse (Note 4)		E_{AS_Limit}	225		mJ
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	36		mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.1		mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	20		A
Continuous Diode Forward Current		I_S	80		A
Diode Pulse Current		$I_{S,PULSE}$	240		A
Operating Junction Temperature		T_J	150		$^{\circ}C$
Storage Temperature		T_{STG}	-55 to 150		$^{\circ}C$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260		$^{\circ}C$

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS} = 12A$, $V_{DD} = 20V$, $R_G = 25\Omega$, Starting $T_J = 25^{\circ}C$
4. $I_{AS_Limit} = 30A$, $V_{DD} = 20V$, $R_G = 25\Omega$, Starting $T_J = 25^{\circ}C$

Thermal Resistance

Parameter		Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	PDFN5*6	R_{thJC}			2.3	$^{\circ}C/W$
	PDFN3.3*3.3	R_{thJC}			2.3	
Thermal Resistance, Junction-to-Ambient	PDFN5*6	R_{thJA}			50	
	PDFN3.3*3.3	R_{thJA}			60	

Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			200	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-200	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=0.25mA$	1.2	1.8	2.4	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$ (DFN5*6)		3.25	3.7	mΩ
		$V_{GS}=10V, I_D=20A$ (DFN3.3*3.3)		3.55	4.1	
		$V_{GS}=4.5V, I_D=5A$ (DFN5*6)		5.4	8.0	
		$V_{GS}=4.5V, I_D=5A$ (DFN3.3*3.3)		5.7	8.5	
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		3.0		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=20V, V_{GS}=0V, f=1MHz$		1.8		nF
Output Capacitance	C_{OSS}			487		pF
Reverse Transfer Capacitance	C_{RSS}			31		pF
Effective output capacitance, energy related NOTE5	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 20V$		760		pF
Effective output capacitance, time related NOTE6	$C_{O(tr)}$			936		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V, I_D=20A$ $R_G=1.6\Omega, V_{GS}=10V$		13		ns
Rise Time	t_r			35		
Turn-off Delay Time	$t_{d(off)}$			40		
Fall Time	t_f			8		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=20V, I_D=20A$ $V_{GS}=0 \text{ to } 10V$		3.9		nC
Gate to Drain Charge	Q_{gd}			3.0		
Gate Charge Total	Q_g			26		
Gate Plateau Voltage	$V_{plateau}$			2.4		V
Gate Charge Total, sync FET	Q_g	$V_{DD}=0.1V, V_{GS}=0 \text{ to } 10V$		24.6		nC
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=20A$		0.82	1.0	V
Reverse Recovery Time	t_{rr}	$V_R=20V, I_F=20A$ $dI_F/dt=100A/\mu s$		46		ns
Reverse Recovery Charge	Q_{rr}			70		nC
Peak Reverse Recovery Current	I_{rrm}			3.1		A

Note:

- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 32V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 32 V



Sanrise Technology Limited Company

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Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.
A1206, Skyworth building, No. 008, gaoxinnan 1st Road,
Gaoxin District, Yuehai street,, Nanshan District, ShenZhen,
P.R.China
Tel: +86-755-22953335
Fax: +86-755-22916878

- Shanghai Office

Sanrise Technology Limited Company
Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China
Tel: +86-21-68825918